

ON Semiconductor®

ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3 / ISL9V3040S3

EcoSPARK® 300mJ, 400V, N-Channel Ignition IGBT

General Description

The ISL9V3040D3S, ISL9V3040S3S, ISL9V3040P3, and ISL9V3040S3 are the next generation ignition IGBTs that offer outstanding SCIS capability in the space saving D-Pak (TO-252), as well as the industry standard D²-Pak (TO-263), and TO-262 and TO-220 plastic packages. This device is intended for use in automotive ignition circuits, specifically as a coil driver. Internal diodes provide voltage clamping without the need for external components.

EcoSPARK® devices can be custom made to specific clamp voltages. Contact your nearest On Semiconductor sales office for more information.

Formerly Developmental Type 49362

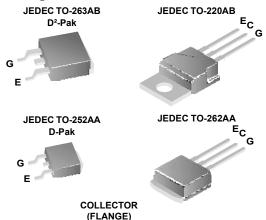
Applications

- · Automotive Ignition Coil Driver Circuits
- · Coil- On Plug Applications

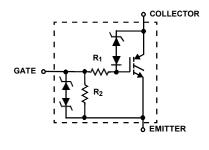
Features

- · Space saving D-Pak package availability
- SCIS Energy = 300mJ at T_J = 25°C
- · Logic Level Gate Drive

Package



Symbol



Device Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
BV _{CER}	Collector to Emitter Breakdown Voltage (I _C = 1 mA)	430		
BV _{ECS}	Emitter to Collector Voltage - Reverse Battery Condition (I _C = 10 mA)	24	V	
E _{SCIS25}	At Starting $T_J = 25^{\circ}C$, $I_{SCIS} = 14.2A$, $L = 3.0$ mHy	300	mJ	
E _{SCIS150}	At Starting T_J = 150°C, I_{SCIS} = 10.6A, L = 3.0 mHy	170	mJ	
I _{C25}	Collector Current Continuous, At T _C = 25°C, See Fig 9	21	Α	
I _{C110}	Collector Current Continuous, At T _C = 110°C, See Fig 9	17	Α	
V_{GEM}	Gate to Emitter Voltage Continuous	±10	V	
P _D	Power Dissipation Total T _C = 25°C	150	W	
	Power Dissipation Derating T _C > 25°C	1.0	W/°C	
TJ	Operating Junction Temperature Range	-40 to 175	°C	
T _{STG}	Storage Junction Temperature Range	-40 to 175	°C	
TL	Max Lead Temp for Soldering (Leads at 1.6mm from Case for 10s)	300	°C	
T _{pkg}	Max Lead Temp for Soldering (Package Body for 10s)	260	°C	
ESD	Electrostatic Discharge Voltage at 100pF, 1500Ω	4	kV	

Device Marking		Device	Package		Reel Size	Tape Width		Quantity	
V3040D		ISL9V3040D3ST	TC	D-252AA	330mm	16mm		2500	
V3040S		ISL9V3040S3ST	TO-263AB		330mm	24mm		800	
V3040P		ISL9V3040P3	TO-220AB		Tube	N/A		50	
V3040S		ISL9V3040S3	TO-262AA		Tube	N/A		50	
V3040D		ISL9V3040D3S	TO-252AA		Tube	N/A		75	
V304		ISL9V3040S3S		D-263AB	Tube		N/A		50
	ai Cha	racteristics T _A = 25°C	C unle			N41			1114
Symbol off State (haract	Parameter		lest Co	nditions	Min	Тур	Max	Units
						070	400	400	
BV _{CER}	Collecto	r to Emitter Breakdown Volta	I_C = 2mA, V_{GE} R_G = 1K Ω , Se T_J = -40 to 150	370	400	430	V		
BV _{CES}	Collector to Emitter Breakdown Voltage			$I_C = 10 \text{mA}, V_{GE} = 0,$		390	420	450	V
020		, and the second		$R_G = 0$, See Fig. 15 $T_J = -40$ to 150°C					
BV _{ECS}	Emitter t	o Collector Breakdown Volta	age	$I_C = -75 \text{mA}, V_{GE} = 0 \text{V},$ $T_C = 25 ^{\circ} \text{C}$		30	-	-	V
BV _{GES}	Gate to I	Emitter Breakdown Voltage		$I_{GES} = \pm 2mA$		±12	±14	-	V
I _{CER}	Collecto	r to Emitter Leakage Curren	t	V _{CER} = 250V,	T _C = 25°C	-	-	25	μA
				$R_G = 1K\Omega$, See Fig. 11	T _C = 150°C	-	-	1	mA
I _{ECS}	Emitter t	o Collector Leakage Curren	t	V _{EC} = 24V, Se		-	-	1	mA
				Fig. 11	T _C = 150°C	-	-	40	mA
R ₁		Sate Resistance				-	70	-	Ω
R ₂ In State (1	Emitter Resistance				10K	-	26K	Ω
V _{CE(SAT)}		r to Emitter Saturation Volta	ge	I _C = 6A,	T _C = 25°C,	-	1.25	1.60	V
	0 11 1 1 5 11 0 1 11 11 11			02	See Fig. 3		4.50	4.00	.,
V _{CE(SAT)}		r to Emitter Saturation Voltaç		I _C = 10A, V _{GE} = 4.5V	T _C = 150°C, See Fig. 4	-	1.58	1.80	V
V _{CE(SAT)}	Collector to Emitter Saturation Voltage		ge	I _C = 15A, V _{GE} = 4.5V	T _C = 150°C	-	1.90	2.20	V
ynamic (Charact	eristics							
$Q_{G(ON)}$	Gate Ch	arge		I _C = 10A, V _{CE} = 12V, V _{GE} = 5V, See Fig. 14		-	17	-	nC
V _{GE(TH)}	Gate to	Emitter Threshold Voltage		I _C = 1.0mA,	T _C = 25°C	1.3	-	2.2	V
				V _{CE} = V _{GE,} See Fig. 10	T _C = 150°C	0.75	-	1.8	V
V_{GEP}	Gate to	Emitter Plateau Voltage		I_C = 10A, V_{CE}	= 12V	-	3.0	-	V
witching	Charac	cteristics							
t _{d(ON)R}	Current	Turn-On Delay Time-Resisti	ve	$V_{CE} = 14V, R_{L} = 1\Omega,$		-	0.7	4	μs
t _{rR}	Current	Rise Time-Resistive		$V_{GE} = 5V$, $R_G = 1K\Omega$ $T_J = 25$ °C, See Fig. 12		-	2.1	7	μs
t _{d(OFF)L}	Current	Turn-Off Delay Time-Inducti	ve	V _{CE} = 300V, L = 500µHy,		-	4.8	15	μs
t _{fL}		Fall Time-Inductive		V_{GE} = 5V, R_G = 1K Ω T _J = 25°C, See Fig. 12		-	2.8	15	μs
SCIS	Self Cla	mped Inductive Switching		T_J = 25°C, L = R_G = 1K Ω , V_G Fig. 1 & 2	-	-	300	mJ	
hermal C	haracte	eristics							
$R_{\theta JC}$	Thorma	Resistance Junction-Case		All packages				1.0	°C/V

Typical Performance Curves

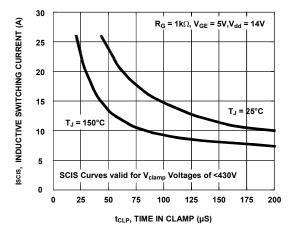
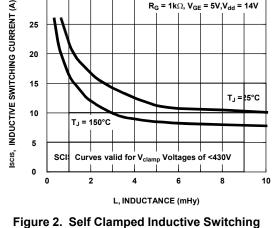


Figure 1. Self Clamped Inductive Switching Current vs Time in Clamp



30

Figure 2. Self Clamped Inductive Switching Current vs Inductance

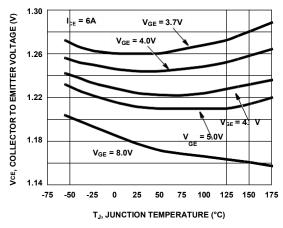


Figure 3. Collector to Emitter On-State Voltage vs Junction Temperature

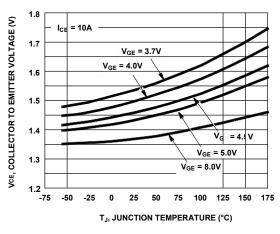


Figure 4. Collector to Emitter On-State Voltage vs Junction Temperature

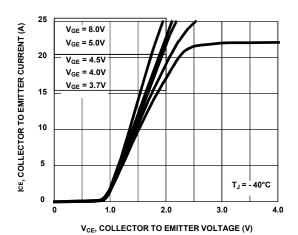


Figure 5. Collector to Emitter On-State Voltage vs Collector Current

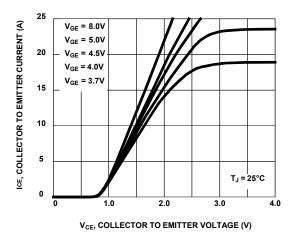


Figure 6. Collector to Emitter On-State Voltage vs Collector Current

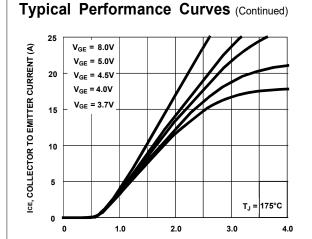


Figure 7. Collector to Emitter On-State Voltage vs Collector Current

V_{CE}, COLLECTOR TO EMITTER VOLTAGE (V)

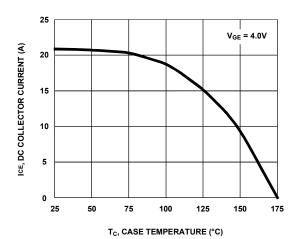


Figure 9. DC Collector Current vs Case Temperature

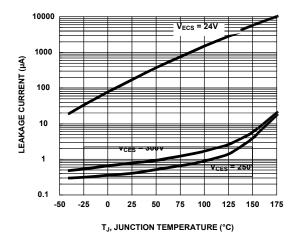


Figure 11. Leakage Current vs Junction Temperature

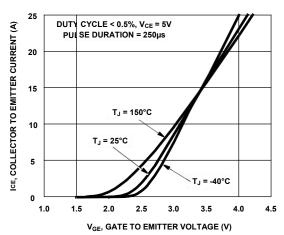


Figure 8. Transfer Characteristics

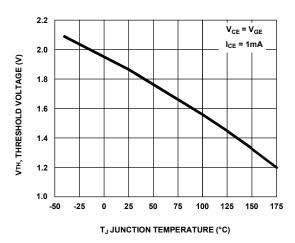


Figure 10. Threshold Voltage vs Junction Temperature

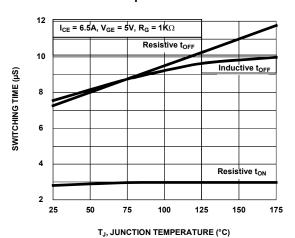
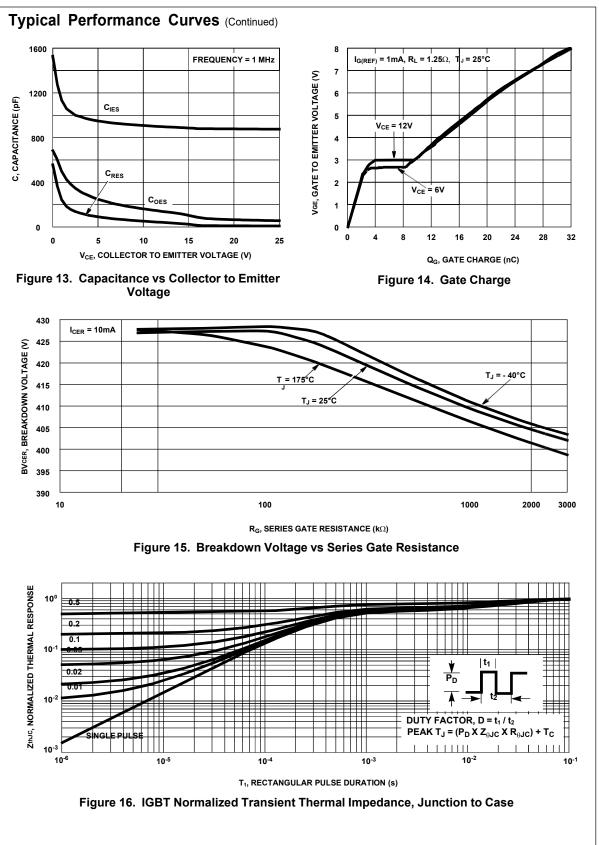


Figure 12. Switching Time vs Junction Temperature



Test Circuit and Waveforms

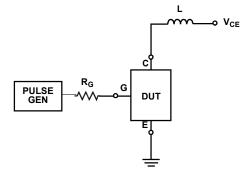


Figure 17. Inductive Switching Test Circuit

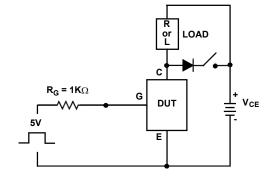


Figure 18. t_{ON} and t_{OFF} Switching Test Circuit

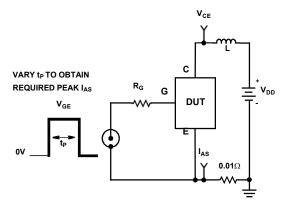


Figure 19. Energy Test Circuit

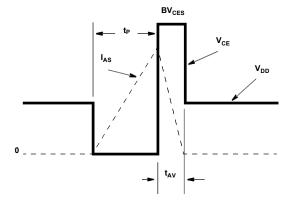


Figure 20. Energy Waveforms

SPICE Thermal Model REV 7 March 2002 JUNCTION ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3 / ISL9V3040S3 CTHERM1 th 6 2.1e -3 CTHERM2 6 5 1.4e -1 CTHERM3 5 4 7.3e -3 CTHERM4 4 3 2.1e -1 RTHERM1 CTHERM1 CTHERM5 3 2 1.1e -1 CTHERM6 2 tl 6.2e +6 RTHERM1 th 6 1.2e -1 6 RTHERM2 6 5 1.9e -1 RTHERM3 5 4 2.2e -1 RTHERM4 4 3 6.0e -2 RTHERM2 CTHERM2 RTHERM5 3 2 5.8e -2 RTHERM6 2 tl 1.6e -3 SABER Thermal Model 5 SABER thermal model ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3 / ISL9V3040S3 RTHERM3 CTHERM3 template thermal model th tl thermal_c th, tl 4 ctherm.ctherm1 th 6 = 2.1e -3 ctherm.ctherm2 6 5 = 1.4e -1 ctherm.ctherm354 = 7.3e - 3ctherm.ctherm4 4 3 = 2.2e -1 RTHERM4 CTHERM4 ctherm.ctherm5 3 2 =1.1e -1 ctherm.ctherm6 2 tl = 6.2e +6 rtherm.rtherm1 th 6 = 1.2e -1 3 rtherm.rtherm2 6 5 = 1.9e -1 rtherm.rtherm3 5 4 = 2.2e -1 rtherm.rtherm4 4 3 = 6.0e-2RTHERM5 CTHERM5 rtherm.rtherm5 3 2 = 5.8e -2 rtherm.rtherm6 2 tl = 1.6e -3 2 RTHFRM6 CTHERM6 CASE

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